

3M joins consortium to accelerate semiconductor technology in the US

ST. PAUL, Minn., Feb. 3, 2025 /PRNewswire/ -- 3M is expanding its commitment to the semiconductor industry by joining the [US-JOINT Consortium](#), a strategic partnership of 12 leading semiconductor suppliers. The consortium drives research and development in next-generation semiconductor advanced packaging and back-end processing technologies anchored by a new cutting-edge facility in Silicon Valley.

"As the demands of AI and other high performance computing technologies increase, suppliers must work together to provide comprehensive solutions to tough challenges on increasingly shorter timelines." said Steven Vander Louw, 3M's president of display and electronics product platforms. "The companies in the US-JOINT Consortium represent US and Japanese innovation leaders in a range of advanced packaging technologies. 3M is pleased to join the consortium in order to bring our decades of materials science expertise, across more than 50 technology platforms, to help address these challenges."

For more than 25 years, 3M has been a supplier of materials and processing aids for semiconductor polishing, advanced packaging, and chip transport applications. Teaming up with industry leaders continues to reinforce 3M's commitment to be an integrated total solutions provider for the semiconductor industry.

The consortium was founded in 2023 and led by Japan-based Resonac, a global leader in the semiconductor and electronics industry.

"We are delighted to welcome 3M to the US-JOINT Consortium," said Hidenori Abe, CTO for semiconductor materials, Resonac. "3M's expertise in materials science and commitment to innovation in advanced packaging device and process solutions will be an asset as we work together to solve difficult technical and integration challenges for customers onshore in the United States."

The new US-JOINT Consortium R&D facility is expected to be unveiled later this year in conjunction with a public launch event.

Learn more about [semiconductor advanced packaging technologies on 3M.com](#).

About 3M

3M believes science helps create a brighter world for everyone. By unlocking the power of people, ideas and science to reimagine what's possible, our global team uniquely addresses the opportunities and challenges of our customers, communities, and planet. Learn how we're working to improve lives and make what's next at [3M.com/news](#).

About the Resonac Group:

The Resonac Group was established in January 2023 as a result of the integration of the Showa Denko Group and the Showa Denko Materials Group (former Hitachi Chemical Group). The Group's annual sales of semiconductor and electronic materials amount to approximately 340 billion yen. The Group is recognized for its extensive lineup of semiconductor materials for back-end processes, which have top market share globally. The integration of the two companies has enabled the Resonac Group to make material design and development in-house from raw materials through to finished goods. The new trade name "RESONAC" was created as a combination of two English words, namely, the word "RESONATE" and "C" from the first letter of CHEMISTRY. The Resonac Group actively leverages its co-creative platform to accelerate technological innovation with semiconductor manufacturers, materials manufacturers, and equipment manufacturers in Japan and across the globe.

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